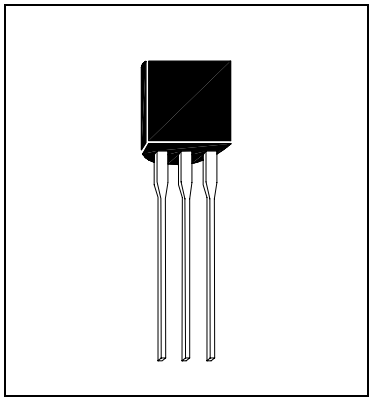
H2N6426

NPN EPITAXIAL PLANAR TRANSISTOR



Description

Darlington Transistor

Absolute Maximum Ratings

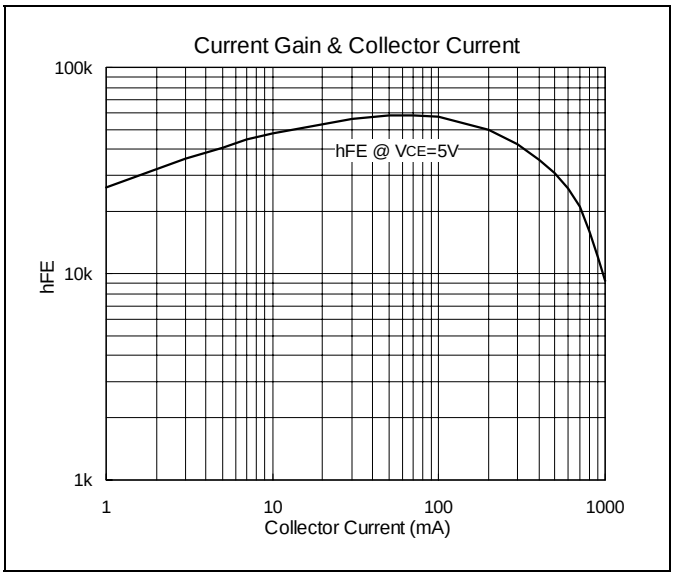
- Maximum Temperatures
  Storage Temperature ..... -55 ~ +150 °C
  Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation
  Total Power Dissipation (Ta=25°C) ..... 625 mW
- Maximum Voltages and Currents (Ta=25°C)
  BVCEO Collector to Emitter Voltage ..... 40 V
  BVCBO Collector to Base Voltage ..... 40 V
  BVEBO Emitter to Base Voltage ..... 12 V
  IC Collector Current ..... 500 mA

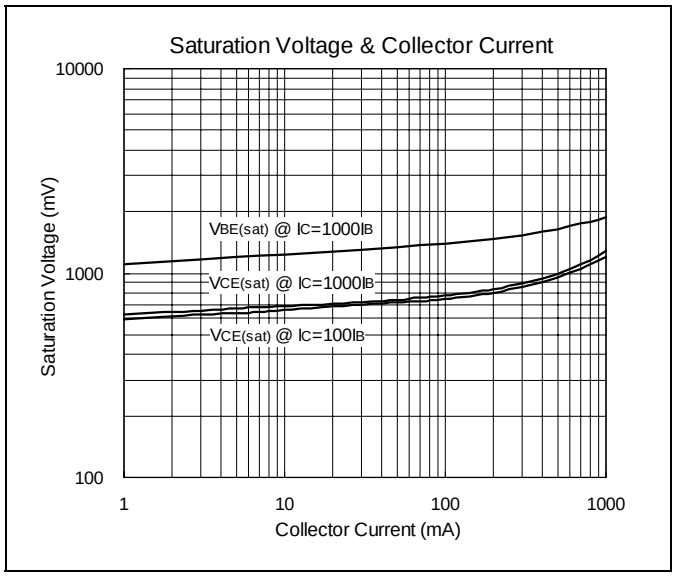
Characteristics (Ta=25°C)

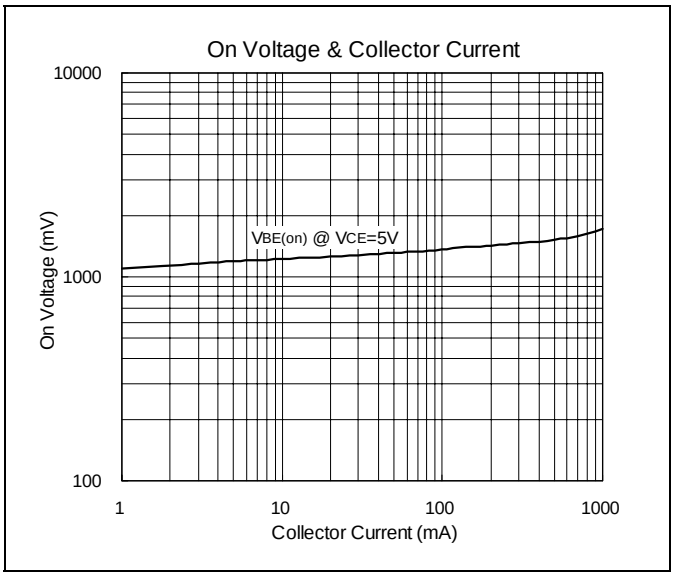
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCEO	40	-	-	V	IC=10mA, IB=0
BVCBO	40	-	-	V	IC=100uA, IE=0
BVEBO	12	-	-	V	IE=10uA, IC=0
ICEO	-	-	1.0	uA	VEB=25V, IB=0
ICBO	-	-	50	nA	VCB=30V, IE=0
IEBO	-	-	50	nA	VEB=10V, IC=0
*VCE(sat)1	-	0.71	1.2	V	IC=50mA, IB=0.5mA
*VCE(sat)2	-	0.9	1.5	V	IC=500mA, IB=0.5mA
*VBE(sat)	-	1.52	2.0	V	IC=500mA, IB=0.5mA
VBE(on)	-	1.24	1.75	V	VCE=5V, IC=50mA
*hFE1	20	-	200	K	VCE=5V, IC=10mA
*hFE2	30	-	300	K	VCE=5V, IC=100mA
*hFE3	20	-	200	K	VCE=5V, IC=500mA
Cob	-	5.4	7.0	pF	VCB=10V, f=1MHz

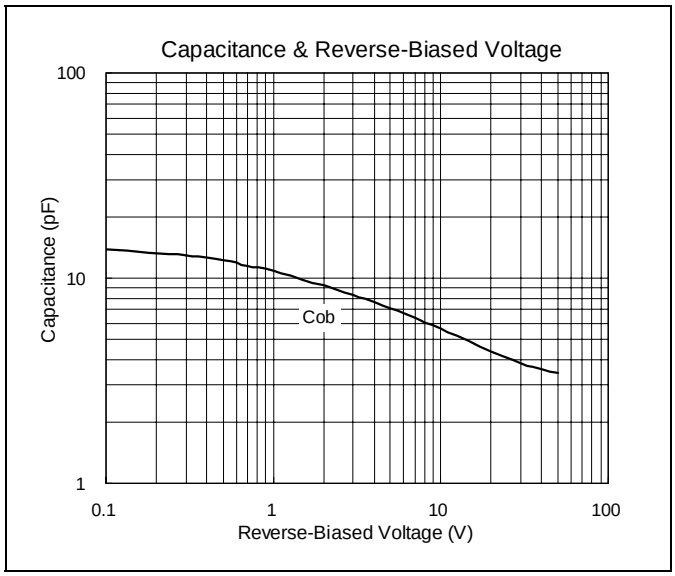
*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

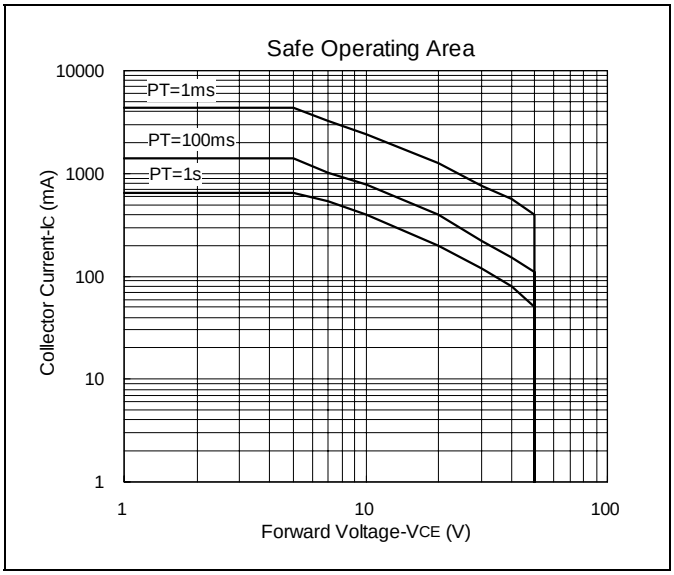
Characteristics Curve

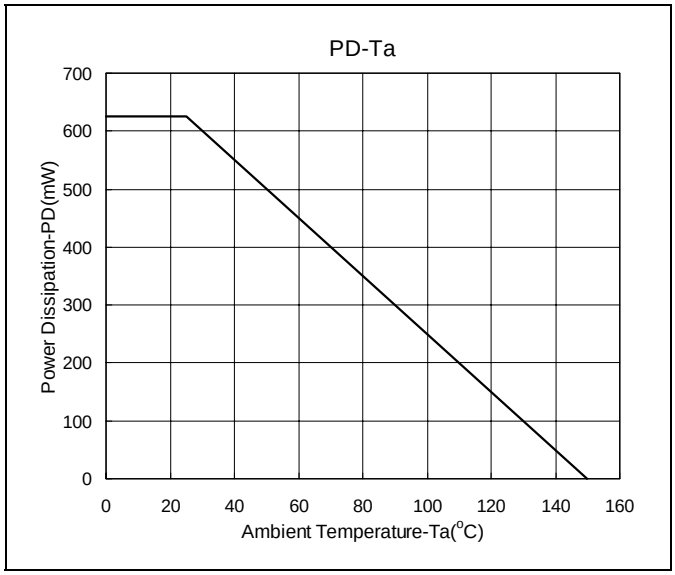




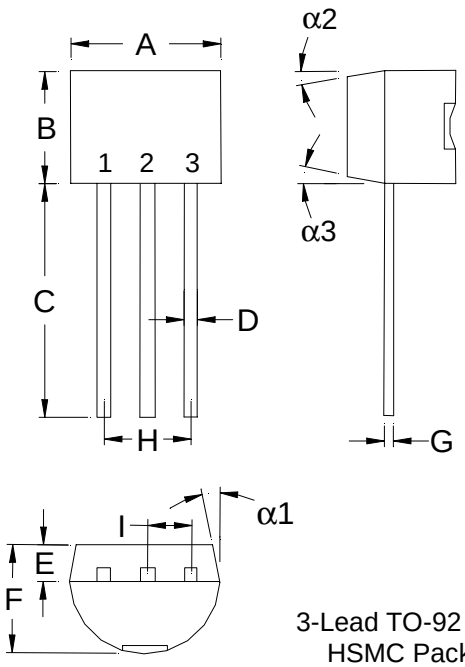






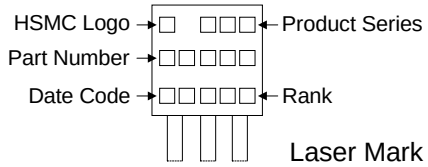


TO-92 Dimension

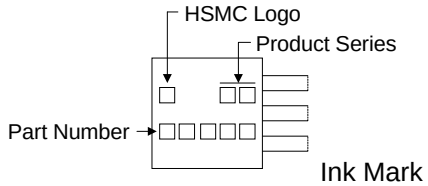


3-Lead TO-92 Plastic Package
HSMC Package Code : A

Marking :



Laser Mark



Ink Mark

Style : Pin 1.Emitter 2.Base 3.Collector

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

Notes : 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
2.Controlling dimension : millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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